

R8019KNX

Nch 800V 19A Power MOSFET

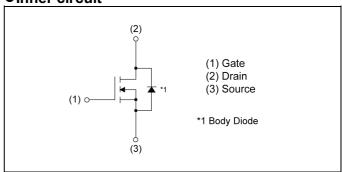
V_{DSS}	800V
R _{DS(on)} (Max.)	0.265Ω
I _D	±19A
P_D	83W

● Package TO-220FM (1)(2)(3)

Features

- 1) Low on-resistance
- 2) Fast switching
- 3) Parallel use is easy
- 4) Pb-free lead plating; RoHS compliant

•Inner circuit



Marking specification

Marking	R8019KNX

Application

Switching

ullet Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V_{DSS}	800	V	
Continuous drain current	I _D *1	±19	Α	
Pulsed drain current		I _{DP} *2	±57	Α
Cata Carma valtaria	static	.,	±20	V
Gate - Source voltage	AC(f>1Hz)	V_{GSS}	±30	V
Avalanche current, single pulse	·	I _{AS}	3.8	Α
Avalanche energy, single pulse		E _{AS} *3	765	mJ
Power dissipation (T _c = 25°C)	P _D	83	W	
Junction temperature	T _j	150	°C	
Operating junction and storage temperature	T _{stg}	-55 to +150	°C	

R8019KNX

Thermal characteristics

Downwortow	Cymah al	Values			l lmit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{th(j-c)} *4	-	-	1.5	°C/W
Thermal resistance, junction - ambient	R _{th(j-a)}	-	-	75	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

● Static characteristics (T_a = 25°C)

Doromotor	Cumbal	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Ofile
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 1mA	800	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 800V, V _{GS} = 0V	1	-	100	μΑ
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 7mA$	2.5	3.5	4.5	V
Static drain - source on - state resistance	R _{DS(on)} *5	$V_{GS} = 10V, I_D = 9.5A$	1	0.220	0.265	Ω

● Dynamic characteristics (T_a = 25°C)

Darramatar	Cymah al	Conditions	Values			Linit	
Parameter	Parameter Symbol Conditions		Min.	Тур.	Max.	Unit	
Gate resistance	R_{G}	f = 1MHz, open drain	-	2.5	1	Ω	
Input capacitance	C _{iss}	V _{GS} = 0V, VDS = 100V	-	2100	1		
Output capacitance	C _{oss}	f = 1MHz	-	120	1		
Effective output capacitance energy related	C _{o(er)} *6	V _{GS} = 0V	-	25	1	pF	
Effective output capacitance time related	C _{o(tr)} *7	V _{DS} = 0V to 400V	-	130	-		
Turn - on delay time	t _{d(on)} *5	V _{DD} ≈ 400V, V _{GS} = 10V	-	35	-		
Rise time	t _r *5	I _D = 9.5A	-	50	-	20	
Turn - off delay time	t _{d(off)} *5	R _L ≃ 42.1Ω	-	110	-	ns	
Fall time	t _f *5	$R_G = 10\Omega$	-	60	-		

• Gate charge characteristics $(T_a = 25^{\circ}C)$

Darameter	Cumb al	Conditions	Values			Unit
Parameter	Symbol Conditions -		Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*5}	V _{DD} ≈ 400V	-	65	1	
Gate - Source charge	Q _{gs} *5	I _D = 19A	-	12	1	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 10V	-	27	-	
Gate plateau voltage	V _(plateau)	V _{DD} ≃ 400V, I _D = 19A	-	5.7	-	V

●Body diode characteristics (Source-Drain) (T_a = 25°C)

Daramatar	Cymahal	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Oill	
Source current	I _S *1	T _C = 25°C	-	-	19	Α	
Pulsed source current	l _{SP} *2		-	-	57	Α	
Source-Drain voltage	V _{SD} *5	V _{GS} = 0V, I _S = 19A	-	-	1.5	٧	
Reverse recovery time	t _{rr} *5		-	730	-	ns	
Reverse recovery charge	Q _{rr} *5	I _S = 19A di/dt = 100A/µs	-	18.5	-	μC	
Peak reverse recovery current	_{rr} *5		-	50	-	Α	

^{*1} Limited only by maximum channel temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L $\stackrel{.}{=}$ 100mH, V_{DD}=50V, R_G=25 Ω , starting T_j=25 $^{\circ}$ C

^{*4} T_C=25°C

^{*5} Pulsed

^{*6} $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as Coss while V_{DS} is rising from 0 to 50% V_{DSS} .

^{*7} $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as Coss while V_{DS} is rising from 0 to 50% V_{DSS} .

• Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

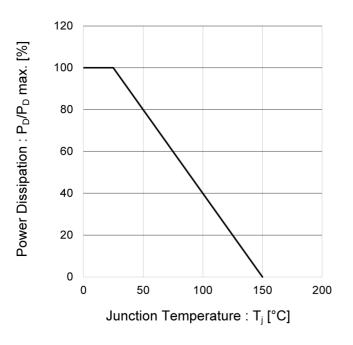


Fig.2 Drain Current Derating Curve

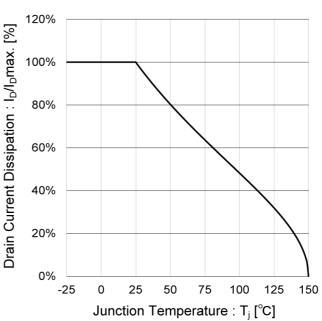


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

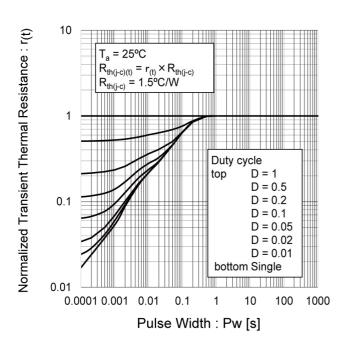
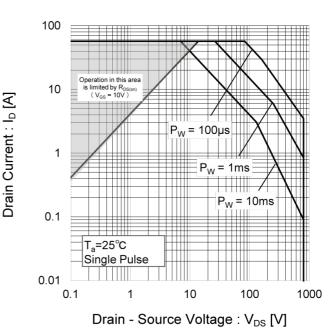


Fig.4 Maximum Safe Operating Area



Electrical characteristic curves

Fig.5 Avalanche Energy Derating Curve

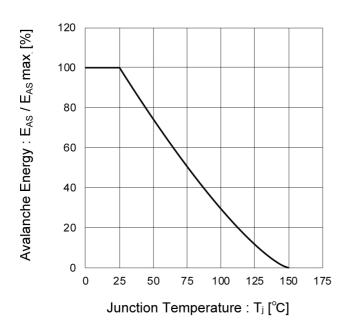


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

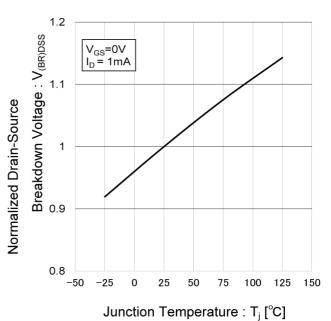


Fig.7 Output Characteristics(I)

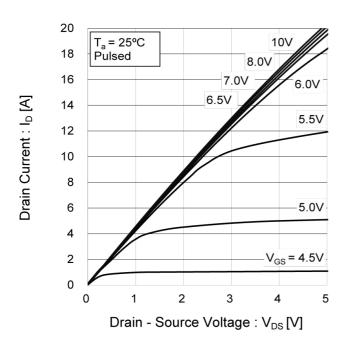
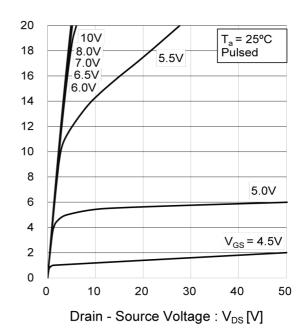


Fig.8 Output Characteristics(II)



Drain Current : I_D [A]

• Electrical characteristic curves

Fig.9 Gate Threshold Voltage vs. Drain current

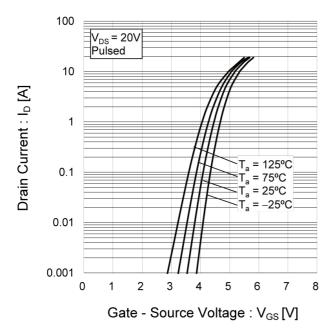


Fig.10 Normalized Gate Threshold

Voltage vs. Junction Temperature

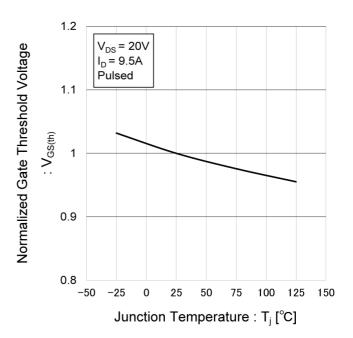


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

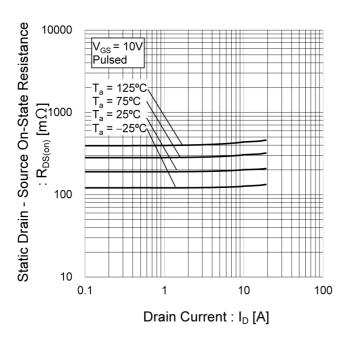
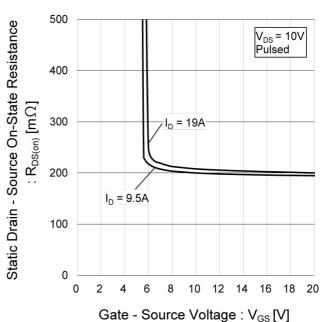


Fig.12 Static Drain - Source On - State Resistance vs. Gate - Source Voltage



Electrical characteristic curves

Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

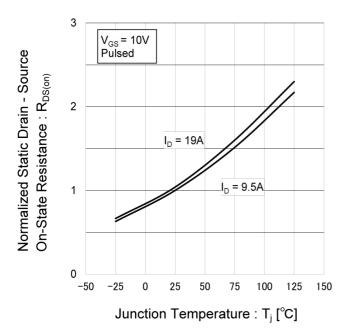
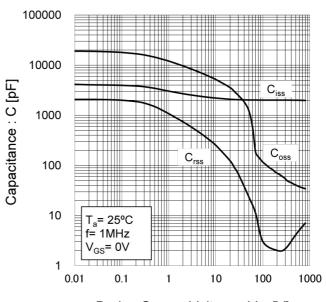


Fig.14 Capacitances



Drain - Source Voltage: V_{DS}[V]

Fig.15 Switching times

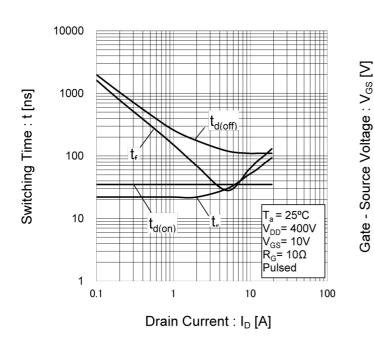
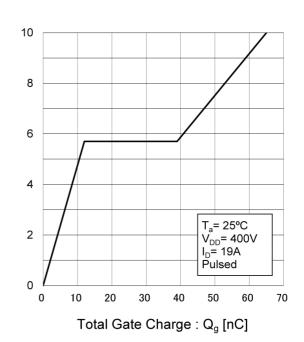


Fig.16 Gate Charge



• Electrical characteristic curves

Fig.17 Source Current vs. Source - Drain Voltage

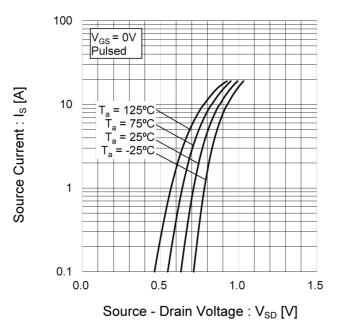
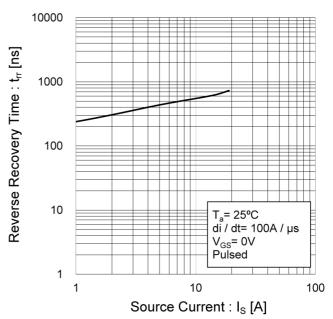


Fig.18 Reverse Recovery Time vs. Source Current



Measurement circuits

Fig.1-1 Switching time measurement circuit

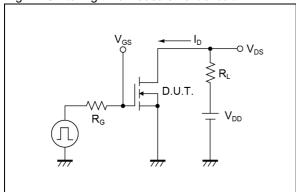


Fig.2-1 Gate charge measurement circuit

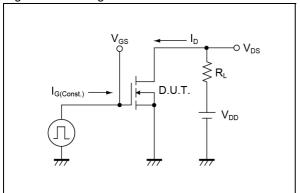


Fig.3-1 Avalanche measurement circuit

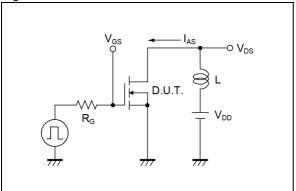


Fig.4-1 trr measurement circuit

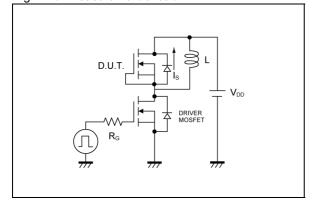


Fig.1-2 Switching waveforms

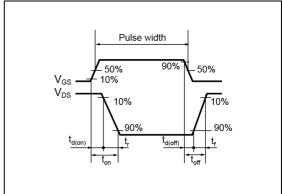


Fig.2-2 Gate charge waveform

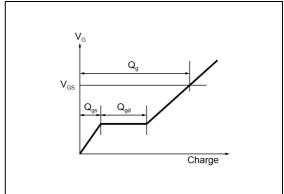


Fig.3-2 Avalanche waveform

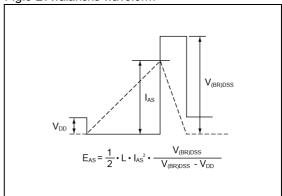
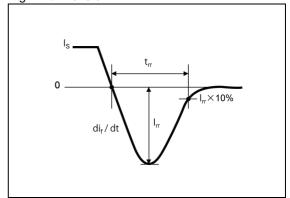
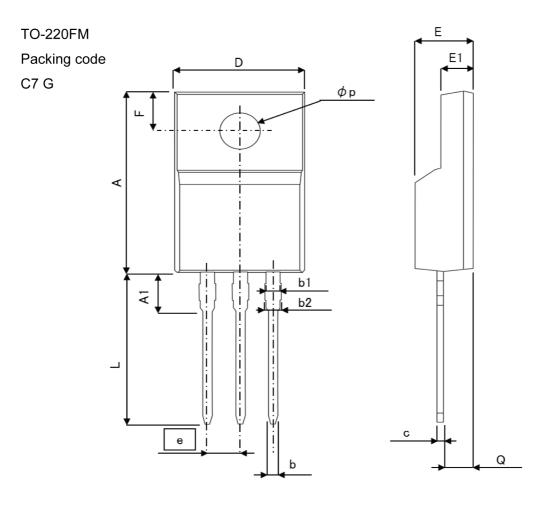


Fig.4-2 trr waveform



Dimensions



DIM	MILIMI	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	15.67	16.27	0.617	0.641
A1	3.03	3.43	0.119	0.135
b	0.70	0.95	0.028	0.037
b1	1.00	1.40	0.039	0.055
b2	1.10	1.50	0.043	0.059
С	0.45	0.65	0.018	0.026
D	9.90	10.30	0.390	0.406
Е	4.60	5.00	0.181	0.197
E1	2.44	2.74	0.096	0.108
е	2.5	54	0.1	00
F	3.10	3.50	0.122	0.138
L	12.6	13.6	0.946	0.535
р	2.98	3.38	0.117	0.133
Q	2.25	3.25	0.089	0.128

Dimension in mm/inches

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JAPAN	USA	EU	CHINA
CLASSⅢ	CL ACCIII	CLASS II b	СГУССШ
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSIII

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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